

FIG. 1

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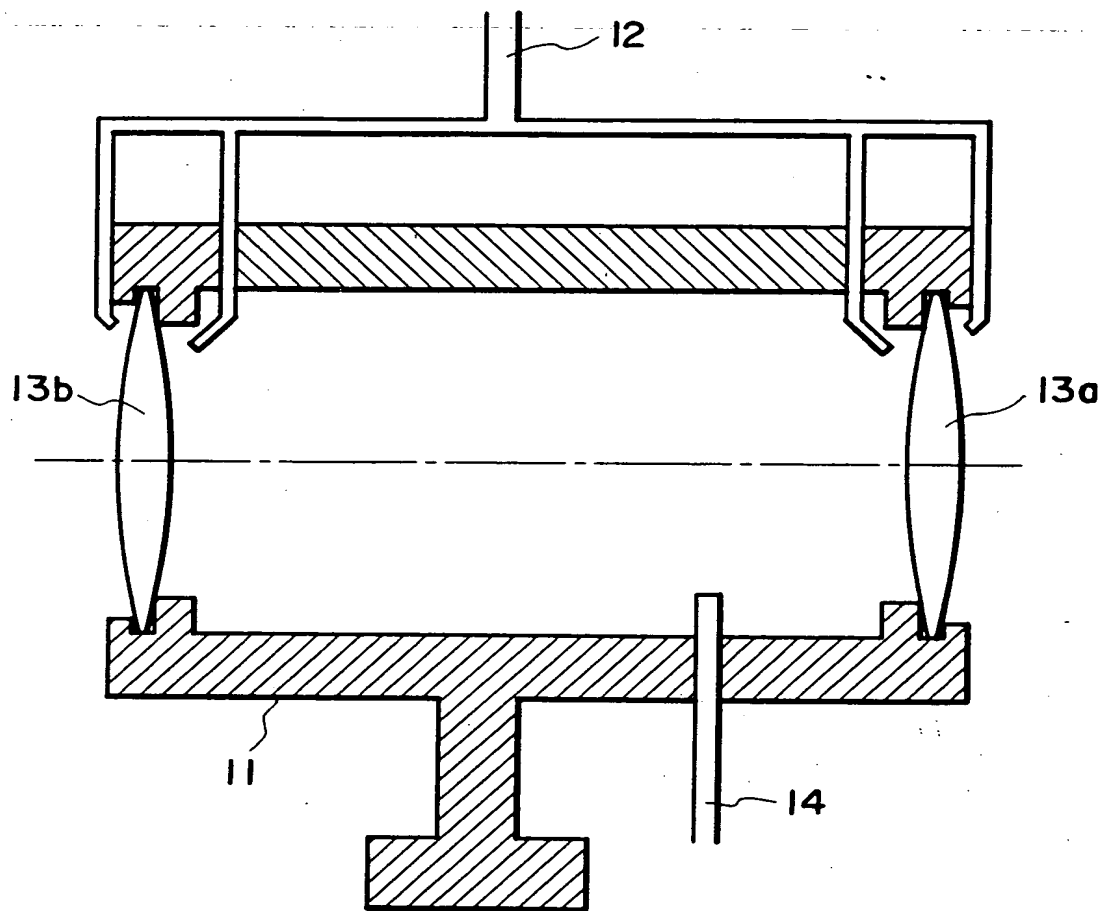


FIG. 2

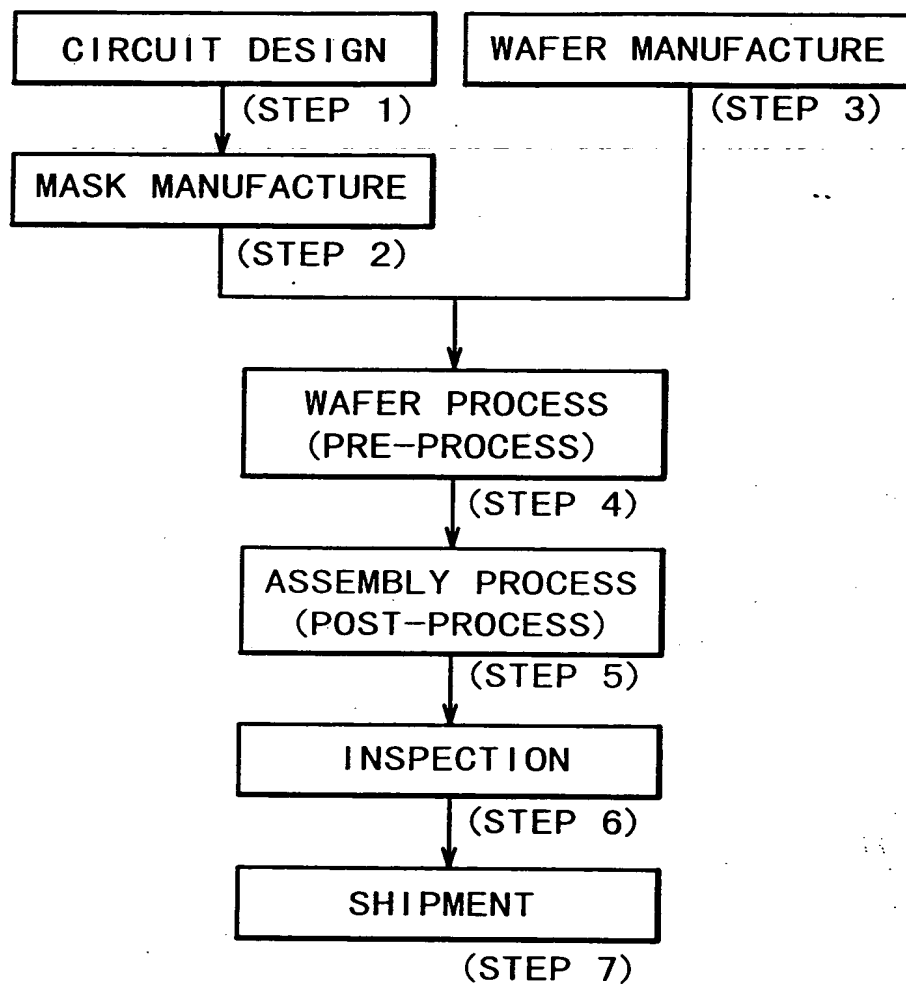


FIG. 3

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graph TD; S1[OXIDATION  
(STEP 11)] --> S2[C V D  
(STEP 12)]; S2 --> S3[ELECTRODE  
FORMATION  
(STEP 13)]; S3 --> S4[ION IMPLANTAION  
(STEP 14)]; S4 --> S5[RESIST PROCESS  
(STEP 15)]; S5 --> S6[EXPOSURE  
(STEP 16)]; S6 --> S7[DEVELOPMENT  
(STEP 17)]; S7 --> S8[ETCHING  
(STEP 18)]; S8 --> S9[RESIST  
SEPARATION  
(STEP 19)]; S9 -- REPEAT --> S1; S1 --> S2; S2 --> S3; S3 --> S4;
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The flowchart illustrates a 19-step semiconductor manufacturing process. It begins with a vertical sequence of four steps: OXIDATION (STEP 11), C V D (STEP 12), ELECTRODE FORMATION (STEP 13), and ION IMPLANTAION (STEP 14). From the final step, the process branches into a second vertical sequence: RESIST PROCESS (STEP 15), EXPOSURE (STEP 16), DEVELOPMENT (STEP 17), ETCHING (STEP 18), and RESIST SEPARATION (STEP 19). A feedback loop labeled 'REPEAT' connects the end of the second sequence back to the beginning of the first sequence, indicating an iterative process.

FIG. 4